

ES51C1D25V-24.000M TR

[Click part number to visit Part Number Details page](#)

REGULATORY COMPLIANCE (Data Sheet downloaded on Feb 14, 2018)


[Click badges to download compliance docs](#)

Regulatory Compliance standards are subject to updates by governing bodies. Click the badges to download the latest compliance docs for this part number directly from Ecliptek.



ITEM DESCRIPTION

Temperature Compensated Quartz Crystal Clock Oscillators TCXO (TCVCXO) Clipped Sinewave 5.0Vdc 10 Pad 5.0mm x 7.0mm Ceramic Surface Mount (SMD) 24.000MHz ± 2.5 ppm Maximum -30°C to +85°C

ELECTRICAL SPECIFICATIONS

Nominal Frequency	24.000MHz
Frequency Stability	± 2.5 ppm Maximum
Frequency Stability vs. Frequency Tolerance	± 1.0 ppm Maximum (Measured at 25°C $\pm 2^\circ\text{C}$, Vdd=5.0Vdc, Vc=1.5Vdc)
Frequency Stability vs. Input Voltage	± 0.2 ppm Maximum (Vdd $\pm 5\%$)
Frequency Stability vs. Load	± 0.2 ppm Maximum ($\pm 1\text{k}\Omega$ / $\pm 1\text{pF}$)
Frequency Stability vs. Aging	± 1 ppm/Year Maximum (at 25°C)
Operating Temperature Range	-30°C to +85°C
Supply Voltage	5.0Vdc $\pm 5\%$
Input Current	2.0mA Maximum
Output Voltage	0.8Vp-p Clipped Sinewave Minimum
Load Drive Capability	10kOhms/10pF
Output Logic Type	Clipped Sinewave
Control Voltage	1.5Vdc ± 1.0 Vdc
Frequency Deviation	± 8 ppm Minimum
Linearity	10% Maximum
Transfer Function	Positive Transfer Characteristic
Modulation Bandwidth	3kHz Minimum (Measured at -3dB with a Control Voltage of 1.5Vdc)
Input Impedance	100kOhms Minimum
Phase Noise	-80dBc/Hz at 10Hz offset, -115dBc/Hz at 100Hz offset, -135dBc/Hz at 1kHz offset, -145dBc/Hz at 10kHz offset, -145dBc/Hz at 100kHz offset (Typical Values, at 12.800MHz)
Start Up Time	5mSec Maximum
Storage Temperature Range	-55°C to +125°C

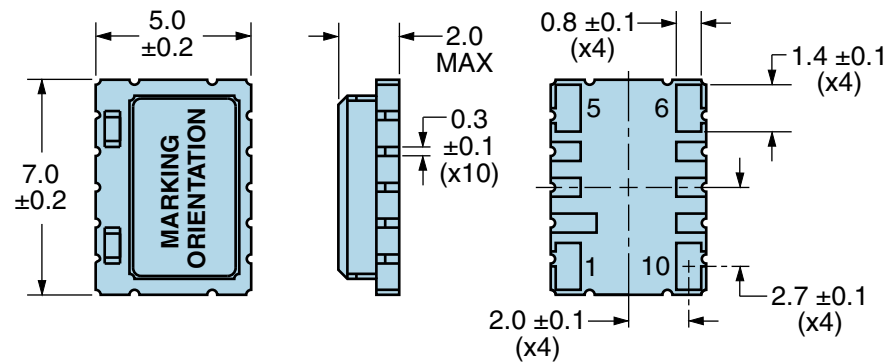
ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

Fine Leak Test	MIL-STD-883, Method 1014 Condition A
Gross Leak Test	MIL-STD-883, Method 1014 Condition C
Mechanical Shock	MIL-STD-202, Method 213 Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010
Vibration	MIL-STD-883, Method 2007 Condition A

ES51C1D25V-24.000M TR

[Click part number to visit Part Number Details page](#)

MECHANICAL DIMENSIONS (all dimensions in millimeters)

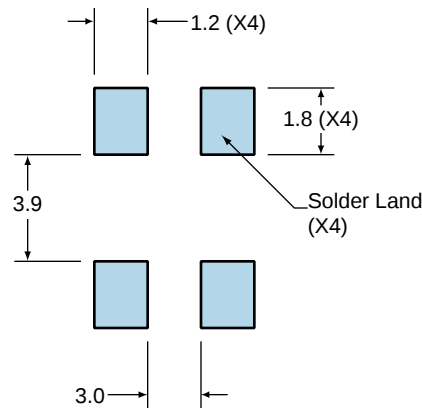


PIN	CONNECTION
1	Voltage Control
2	Do Not Connect
3	Do Not Connect
4	Do Not Connect
5	Case/Ground
6	Output
7	Do Not Connect
8	Do Not Connect
9	Do Not Connect
10	Supply Voltage

LINE	MARKING
1	E24.000 E=Ecliptek
2	XXYYZ XX=Ecliptek Manufacturing Code Y=Last Digit of the Year ZZ=Week of the Year

Suggested Solder Pad Layout

All Dimensions in Millimeters

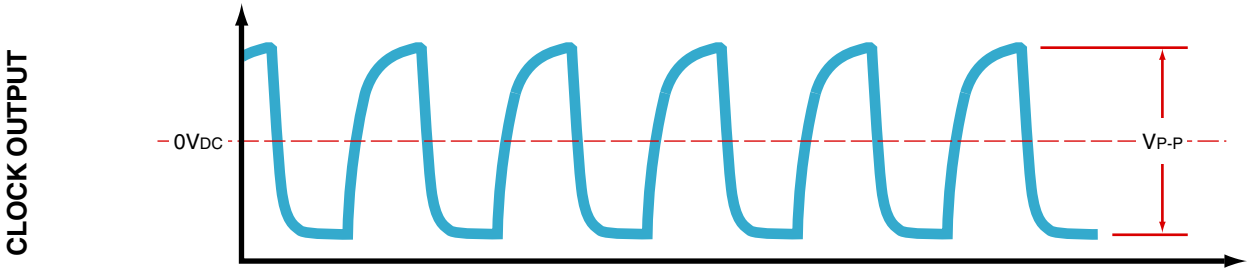


All Tolerances are ±0.1

ES51C1D25V-24.000M TR

[Click part number to visit Part Number Details page](#)

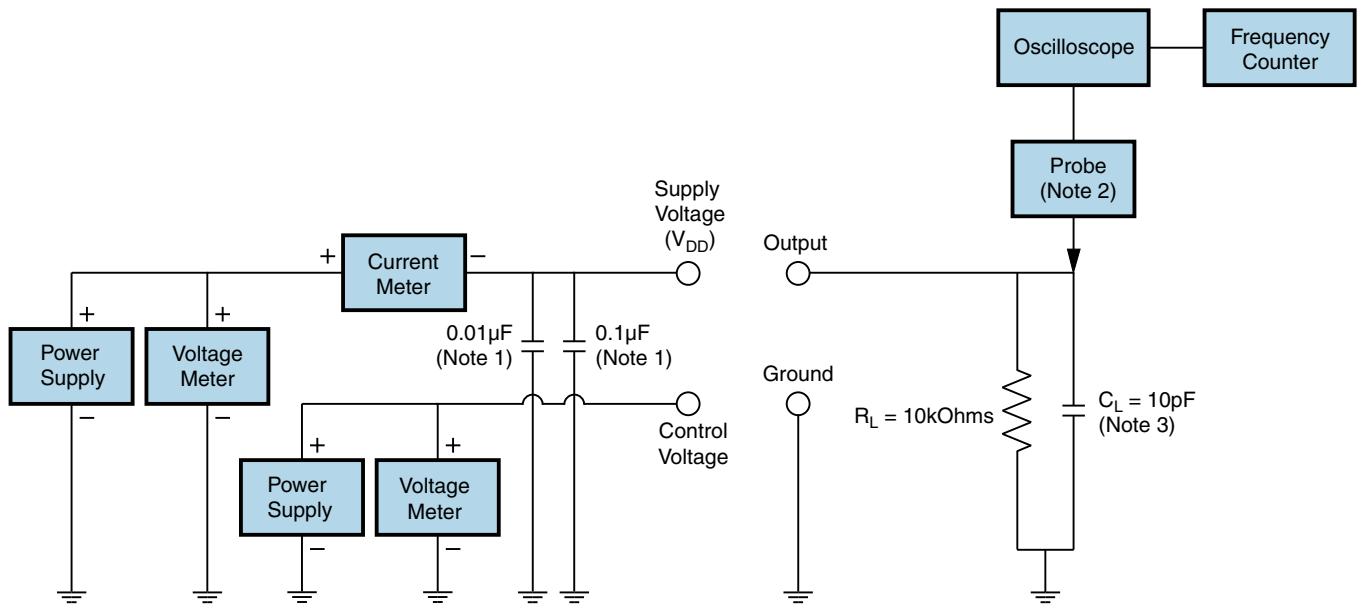
OUTPUT WAVEFORM



ES51C1D25V-24.000M TR

[Click part number to visit Part Number Details page](#)

Test Circuit for Control Voltage Option



Note 1: An external 0.01µF bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low input capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value C_L includes sum of all probe and fixture capacitance.

ES51C1D25V-24.000M TR

Tape & Reel Dimensions

Quantity Per Reel: 1,000 units

All Dimensions in Millimeters

Compliant to EIA-481



ES51C1D25V-24.000M TR

[Click part number to visit Part Number Details page](#)

Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 220°C

TS MAX to TL (Ramp-up Rate)	5°C/Second Maximum
Preheat	
- Temperature Minimum (TS MIN)	N/A
- Temperature Typical (TS TYP)	150°C
- Temperature Maximum (TS MAX)	N/A
- Time (ts MIN)	60 - 120 Seconds
Ramp-up Rate (TL to TP)	5°C/Second Maximum
Time Maintained Above:	
- Temperature (TL)	150°C
- Time (tL)	200 Seconds Maximum
Peak Temperature (TP)	220°C Maximum
Target Peak Temperature (TP Target)	220°C Maximum 1 Time / 215°C Maximum 1 Time
Time within 5°C of actual peak (tP)	15 Seconds Maximum 1 Time / 80 Seconds Maximum 1 Time
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures listed are applied to body of device.

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures listed are applied to body of device.)

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures listed are applied to body of device.)